

# PRODUCT DATA SHEET

# NC-699

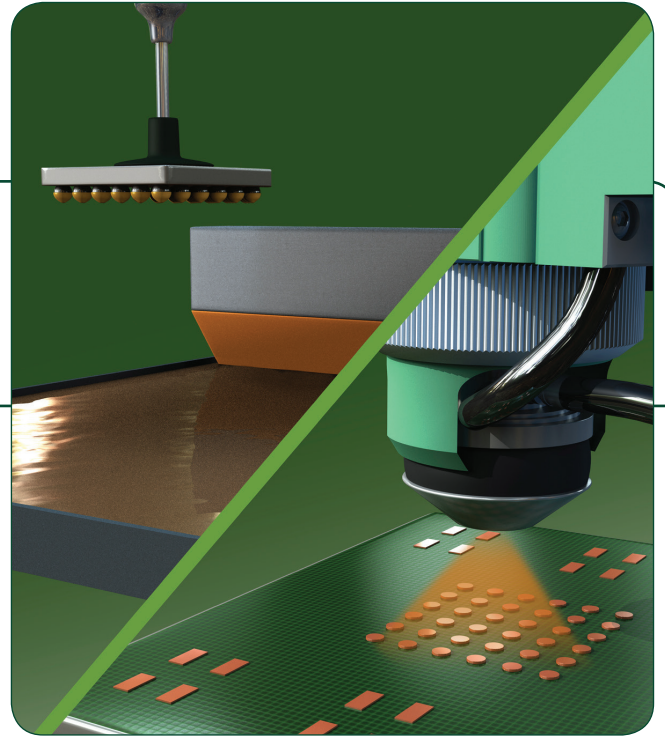
## Flip-Chip Flux

### Introduction

**Flip-Chip Flux NC-699** is a halogen-free, no-clean flip-chip dipping flux, which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

### Features

- Designed for copper-pillar flip-chip dipping applications
- Suitable for Pb-free alloys
- Designed for MEMS devices >1mm<sup>2</sup>
- Bubble-free airless packaging
- Ultra-low residue
- Halogen-free
- No-clean



### Properties

	Value	Test Method
Flux Type	ORLO	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light yellow	Visual
Typical Viscosity	1,475cps	Brookfield DV-I, 40CPE Spindle @ 10rpm after 3 minutes
Typical Acid Value	39mg KOH/g	Titration
SIR (Ohms)	Pass	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Post Reflow Residual Weight	<5%	TGA data
Working Life	≥8 hours	Customer experience (dipping)
Shelf Life	1 year when stored at 0 to 30°C	Viscosity change/ microscope examination

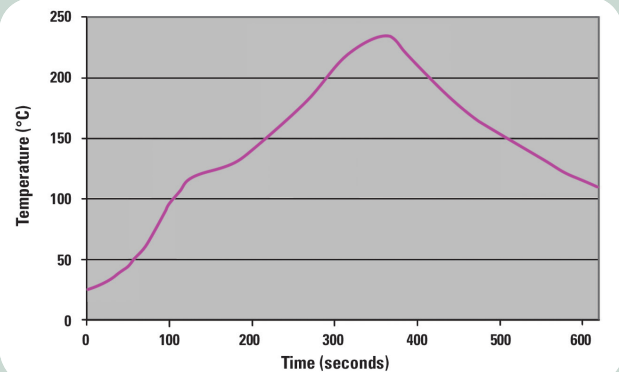
*All information is for reference only.  
Not to be used as incoming product specifications.*

### Application

**Flip-Chip Flux NC-699** will have strong adhesion to epoxy-based underfill materials, especially epoxy-amine and epoxy-acid based chemistries. **Flip-Chip Flux NC-699** should also be suitable for use with many epoxy-anhydride systems.

### Reflow

#### Recommended Profile:



**Flip-Chip Flux NC-699** is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **Flip-Chip Flux NC-699** can be used on many surface finishes including immersion Ag, Cu, and AuNi. These surfaces can be soldered with Pb-free alloys, but require nitrogen if reflow temperatures exceed 240°C.

**From One Engineer To Another®**



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### Cleaning

**Flip-Chip Flux NC-699** is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Support Engineer for recommendations of cleaners to suit your process needs.

### Packaging

**Flip-Chip Flux NC-699** is most commonly available in containers from 100g to 3.2kg (1 gallon). Other packaging can be provided to meet specific requirements.

### Storage

**Flip-Chip Flux NC-699** containers should be stored at 0 to 30°C for maximum shelf life. **Flip-Chip Flux NC-699** should be allowed to reach ambient temperature before use if stored cold.

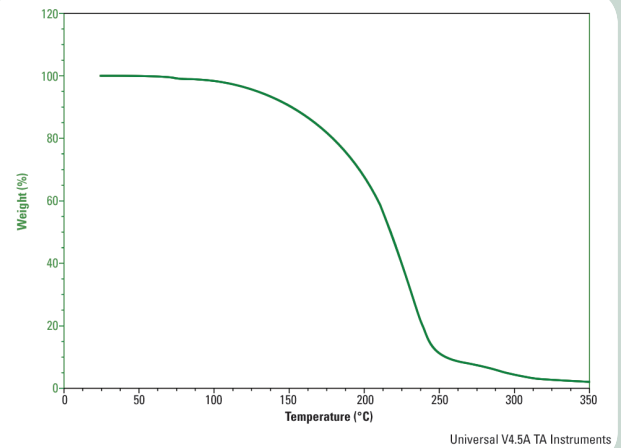
### Technical Support

Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

### Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

### Thermogravimetric Analysis (TGA)



TGA was performed at a ramp rate of 10°C per minute.

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Contact our engineers today: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com](http://www.indium.com)

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900

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